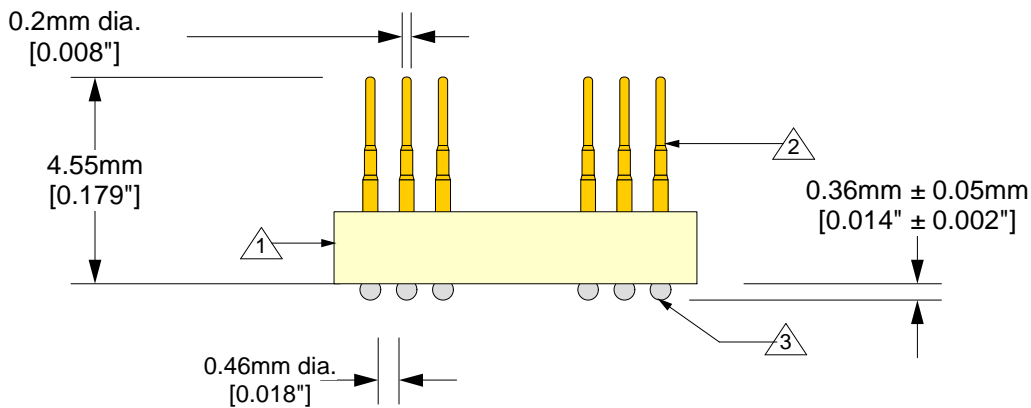


Top View




Side View

- 1 Substrate: 1.59mm  $\pm$ 0.18mm [0.0625"  $\pm$ 0.007"]  
FR4/G10 or equivalent high temp material;  
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25 $\mu$ m [10 $\mu$ ] Au over 1.27 $\mu$ m [50 $\mu$ ] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

**Description:** Giga-snaP BGA SMT Foot

60 position terminal pins (0.8mm centers, 8x10 array) to SMT solder balls (BGA type). Pin assignment 1:1.

**Tolerances:** diameters  $\pm$ 0.03mm [ $\pm$ 0.001"], PCB perimeters  $\pm$ 0.13mm [ $\pm$ 0.005"], PCB thicknesses  $\pm$ 0.18mm [ $\pm$ 0.007"], pitches (from true position)  $\pm$ 0.08mm [ $\pm$ 0.003"], all other tolerances  $\pm$ 0.13mm [ $\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

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	<p>Drawing: M.A. Fedde</p>	<p>Date: 2/25/08</p>	<p>File: SF-BGA60C-B-61F Dwg.mcd</p>	<p>Modified: 07/01/14</p>